

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
QINGLONG ZENG	11/06/2019
RECEIVING PARTY DATA	
Name:	SHENZHEN AMI TECHNOLOGY CO. LTD.
Street Address:	1/F, H2 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK
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City:	SHENZHEN
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16532614
CORRESPONDENCE DATA	
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SIGNATURE:	/Salvatore Anastasi/
DATE SIGNED:	02/10/2020
Total Attachments: 1	
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COMBINED DECLARATION AND ASSIGNMENT

As a below named and signing inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

- the attached application, or
- United States application or PCT international application number 16/532,614 filed on August 6, 2019, entitled AUTOMATIC SOLDER PASTE FEEDING SYSTEM

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

SHENZHEN AMI TECHNOLOGY CO. LTD., a corporation organized and existing under and by virtue of the laws of China, having its principal place of business at 1/F, H2 Bldg, Hongfa Hi-tech Industrial Park Tangtou Blvd., Hiyuan, Baoan District, Guangdong, Shenzhen, China,

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer, and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries, including all priority rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof; and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment.

Legal Name	Signature	Date
Qinglong ZENG	<i>Qinglong Zeng</i>	2019.11.6